THE DATASHEET OF

BAS40LP-7

Features

- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Leadless Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: X1-DFN1006-2
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Marking Information
- Terminals: Finish - NiPdAu Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 e4
- Weight: 0.001 grams (Approximate)

X1-DFN1006-2

Top View

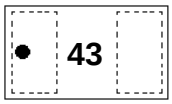
Bottom View

Ordering Information (Note 4)

Part Number	Case	Packaging
BAS40LP-7	X1-DFN1006-2	3,000/Tape & Reel
BAS40LP-7B	X1-DFN1006-2	10,000/Tape & Reel

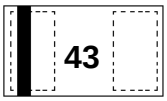
Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

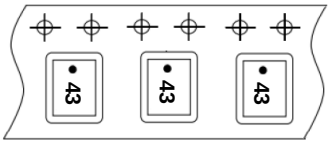


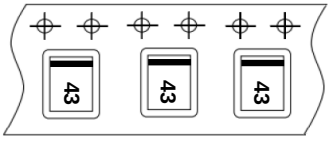
Top View
Dot Denotes Cathode Side

From date code 1527 (YYWW), this changes to:



Top View
Bar Denotes Cathode Side





43 = Part Marking Code

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	40	V
Forward Continuous Current	I_{FM}	200	mA
Repetitive Peak Forward Current (Note 6)	I_{FRM}	800	mA
Non-Repetitive Peak Forward Surge Current @ t_p = 1.0s (Note 7)	I_{FSM}	1,000	mA

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation	P_D	250	mW
Typical Thermal Resistance, Junction to Ambient (Note 8)	$R_{\theta JA}$	400	°C/W
Operating Temperature Range	T_J	-55 to +150	°C
Storage Temperature Range	T_{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	V_R	40	—	—	V	I_R = 10μA
Forward Voltage (Note 5)	V_F	—	—	380 1,000	mV	t_p < 300μs, I_F = 1.0mA t_p < 300μs, I_F = 40mA
Reverse Leakage Current (Note 5)	I_R	—	20	200	nA	t_p < 300μs, V_R = 30V
Total Capacitance	C_T	—	2.3	5.0	pF	V_R = 0V, f = 1.0MHz
Reverse Recovery Time	t_{RR}	—	—	5.0	ns	I_F = I_R = 10mA to I_R = 1.0mA, R_L = 100Ω

Notes:
5. Short duration pulse test used to minimize self-heating effect.
6. Repetitive peak forward current was tested with $t_p \leq$ 1s and $\partial \leq 0.8$ square wave.
7. Non-repetitive peak forward current was tested with t_p = 1s square wave.
8. 1*MRP FR-4 PC board 2oz.Copper, minimum recommended pad layout per http://www.diodes.com/package-outlines.html.

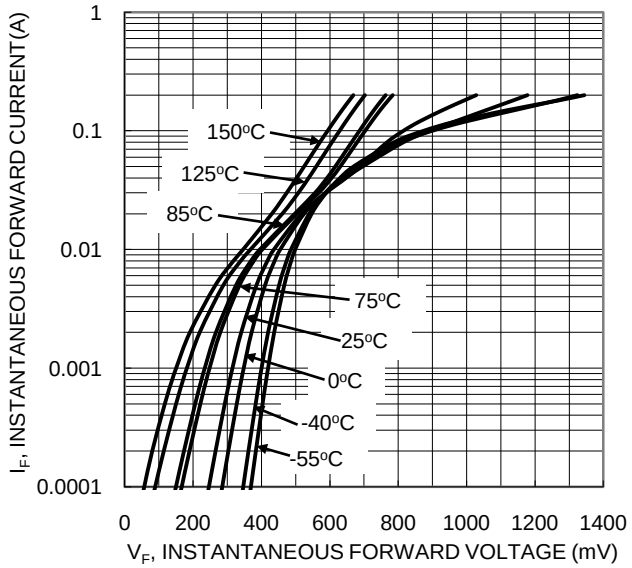


Fig.1 Typical Forward Voltage

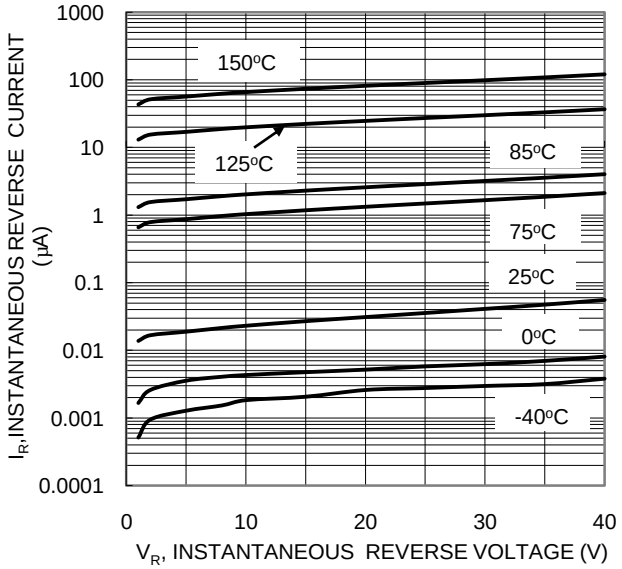


Fig.2 Typical Reverse Characteristics

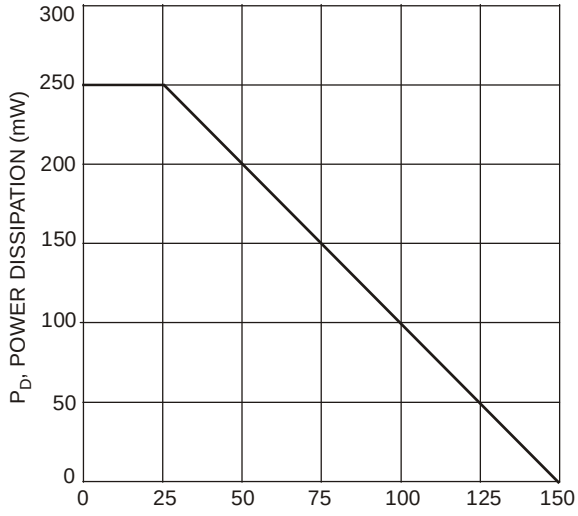


Fig. 3 Power Derating Curve

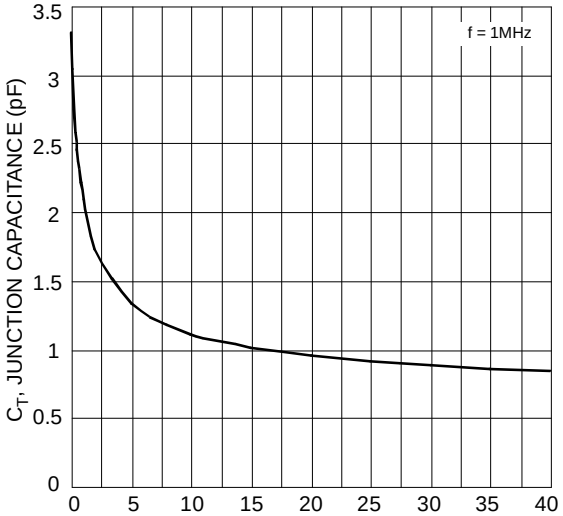


Fig. 4 Typical Junction Capacitance

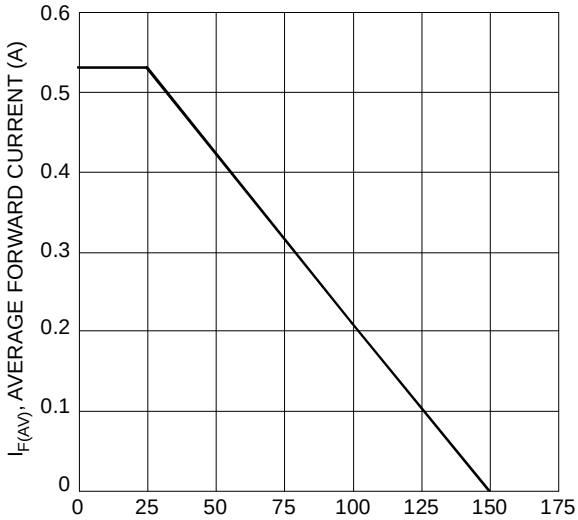


Fig. 5 Forward Current Derating Curve

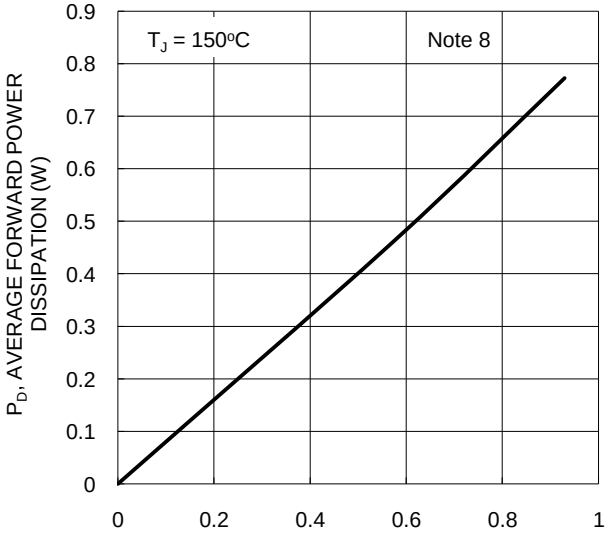


Fig.6 Forward Power Dissipation

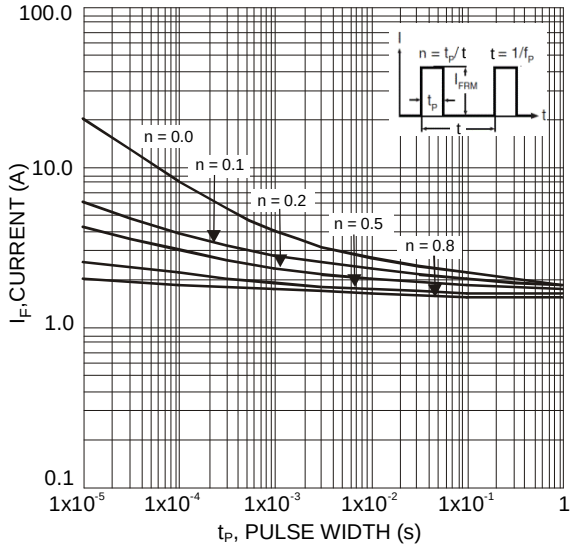
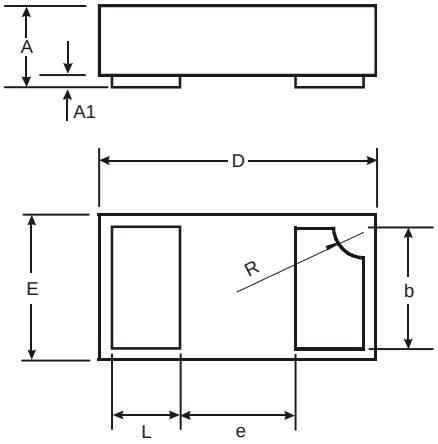


Fig. 7 Repetitive Forward Current with Pulse Duration

Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1006-2

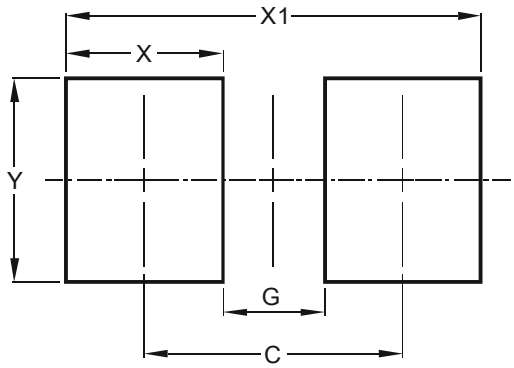


X1-DFN1006-2			
Dim	**Min**	**Max**	**Typ**
A	0.47	0.53	0.50
A1	0	0.05	0.03
b	0.45	0.55	0.50
D	0.95	1.075	1.00
E	0.55	0.675	0.60
e	-	-	0.40
L	0.20	0.30	0.25
R	0.05	0.15	0.10
All Dimensions in mm			

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1006-2



Dimensions	Value (in mm)
C	0.70
G	0.30
X	0.40
X1	1.10
Y	0.70

IMPORTANT NOTICE

DIODES INCORPORATED MAKES NO WARRANTY OF ANY KIND, EXPRESS OR IMPLIED, WITH REGARDS TO THIS DOCUMENT, INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION).

Diodes Incorporated and its subsidiaries reserve the right to make modifications, enhancements, improvements, corrections or other changes without further notice to this document and any product described herein. Diodes Incorporated does not assume any liability arising out of the application or use of this document or any product described herein; neither does Diodes Incorporated convey any license under its patent or trademark rights, nor the rights of others. Any Customer or user of this document or products described herein in such applications shall assume all risks of such use and will agree to hold Diodes Incorporated and all the companies whose products are represented on Diodes Incorporated website, harmless against all damages.

Diodes Incorporated does not warrant or accept any liability whatsoever in respect of any products purchased through unauthorized sales channel. Should Customers purchase or use Diodes Incorporated products for any unintended or unauthorized application, Customers shall indemnify and hold Diodes Incorporated and its representatives harmless against all claims, damages, expenses, and attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized application.

Products described herein may be covered by one or more United States, international or foreign patents pending. Product names and markings noted herein may also be covered by one or more United States, international or foreign trademarks.

This document is written in English but may be translated into multiple languages for reference. Only the English version of this document is the final and determinative format released by Diodes Incorporated.

LIFE SUPPORT

Diodes Incorporated products are specifically not authorized for use as critical components in life support devices or systems without the express written approval of the Chief Executive Officer of Diodes Incorporated. As used herein:

A. Life support devices or systems are devices or systems which:

1. are intended to implant into the body, or

2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systems-related information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

www.diodes.com

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- View BAS40LP-7 on WIN SOURCE
- Diodes Incorporated Information

Optimize Your Supply Chain with WIN SOURCE Solutions

- Global Sourcing Solution
- Obsolete Management
- Cost Control Management
- Shortage Management
- Alternative Solution
- Excess Inventory Management